



QFS-078-04.25-L-D-PC4

QFS-052-04.25-L-D-RF1

Community Summunity

**QFS-PC, QFS-RF SERIES** 

(0.635 mm) .025"

# **HIGH-SPEED COMBO RF & POWER**

# SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?QFS

Insulator Material: Liquid Crystal Polymer Contact & Ground Plane Material: Phosphor Bronze Plating: Au over 50 μ" (1.27 μm) Ni (Tin on Ground Plane Tail) Current Rating: Signal Contact: 2.6 A per pin (2 pins powered) Power Contact: 4.0 A per pin (4 pins powered per end) Ground Plane: 15.7 A per ground plane (1 ground plane powered) Voltage Rating: 300 VAC mated with QMS Operating Temp: -55 °C to +125 °C **RoHS Compliant:** 

# PROCESSING

Lead-Free Solderable: Yes SMT Lead Coplanarity: (0.10 mm) .004" max (026-078) Board Stacking: For applications requiring more than two connectors per board, contact ipg@samtec.com

### RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



#### **ALSO AVAILABLE** (MOQ Required)

- Other platings
- Differential Pairs
- Retention Pins
- 8 Power Pins/End for (1.60 mm) .062" thick board
- 4 or 8 Power Pins/End for (2.36 mm) .093" thick board
- 2 RF Connectors/End
- · Hot Pluggable

Note: Some lengths, styles and options are non-standard,

non-returnable.



#### Due to technical progress, all designs, specifications and components are subject to change without notice WWW.SAMTEC.COM

All parts within this catalog are built to Samtec's specifications. Customer specific requirements must be approved by Samtec and identified in a Samtec customer-specific drawing to apply.